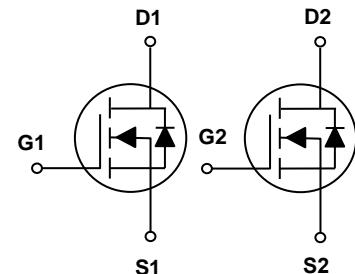
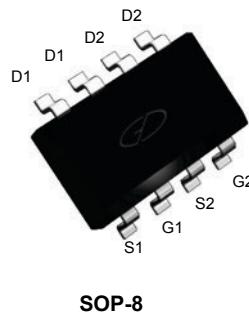


Main Product Characteristics

$V_{(BR)DSS}$	10V
$R_{DS(ON)}$	18mΩ
I_D	8A



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The SSFE utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

Absolute Maximum Ratings ($T_C=25^\circ C$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	V_{DS}	40	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous($T_A=25^\circ C$)	I_D	8	A
Drain Current-Continuous($T_A=70^\circ C$)		6.4	A
Drain Current-Pulsed ¹	I_{DM}	32	A
Single Pulse Avalanche Energy ²	E_{AS}	4.9	mJ
Single Pulse Avalanche Current ²	I_{AS}	9.9	A
Power Dissipation($T_A=25^\circ C$)	P_D	2	W
Power Dissipation-Derate Above 25°C		0.016	W/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	°C/W
Storage Temperature Range	T_{STG}	-50 To +150	°C
Operating Junction Temperature Range	T_J	-50 To +150	°C

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	40	-	-	V
Drain-Source Leakage Current	I_{DSS}	$V_{\text{DS}}=40\text{V}, V_{\text{GS}}=0\text{V}, T_J=25^\circ\text{C}$	-	-	1	μA
		$V_{\text{DS}}=32\text{V}, V_{\text{GS}}=0\text{V}, T_J=125^\circ\text{C}$	-	-	10	μA
Gate-Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
On Characteristics						
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=8\text{A}$	-	16	18	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=4\text{A}$	-	20	25	
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.2	1.6	2.5	V
Forward Transconductance	g_{fs}	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=1\text{A}$	-	5	-	S
Dynamic and Switching Characteristics						
Total Gate Charge ^{2,3}	Q_g	$V_{\text{DS}}=32\text{V}, I_{\text{D}}=3\text{A}, V_{\text{GS}}=10\text{V}$	-	10.8	21.6	nC
Gate-Source Charge ^{2,3}	Q_{gs}		-	1.6	3.2	
Gate-Drain Charge ^{2,3}	Q_{gd}		-	3.3	6.6	
Turn-On Delay Time ^{2,3}	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=15\text{V}, R_{\text{G}}=3.3\Omega, V_{\text{GS}}=10\text{V}, I_{\text{D}}=1\text{A}$	-	3.8	7.6	nS
Rise Time ^{2,3}	t_r		-	10.5	21	
Turn-Off Delay Time ^{2,3}	$t_{\text{d}(\text{off})}$		-	22.2	45	
Fall Time ^{2,3}	t_f		-	6.6	13.2	
Input Capacitance	C_{iss}	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, F=1\text{MHz}$	-	724	1450	PF
Output Capacitance	C_{oss}		-	70	140	
Reverse Transfer Capacitance	C_{rss}		-	109	220	
Gate Resistance	R_g	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\text{V}, F=1\text{MHz}$	-	2.6	-	Ω
Drain-Source Diode Characteristics and Maximum Ratings						
Continuous Source Current	I_s	$V_G=V_D=0\text{V}, \text{Force Current}$	-	-	8	A
Pulsed Source Current	I_{SM}		-	-	16	A
Diode Forward Voltage	V_{SD}	$V_{\text{GS}}=0\text{V}, I_s=1\text{A}, T_J=25^\circ\text{C}$	-	-	1	V
Reverse Recovery Time	T_{rr}	$V_R=30\text{V}, I_s=8\text{A}, di/dt=100\text{A}/\mu\text{s}, T_J=25^\circ\text{C}$	-	33	-	nS
Reverse Recovery Charge	Q_{rr}		-	12	-	nC

Note:

- Repetitive Rating: Pulsed width limited by maximum junction temperature.
- $V_{\text{DD}}=25\text{V}, V_{\text{GS}}=10\text{V}, L=0.1\text{mH}, I_{\text{AS}}=9.9\text{A}, R_{\text{G}}=25\Omega$, Starting $T_J=25^\circ\text{C}$.
- The data tested by pulsed, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
- Essentially independent of operating temperature.

Typical Electrical and Thermal Characteristic Curves

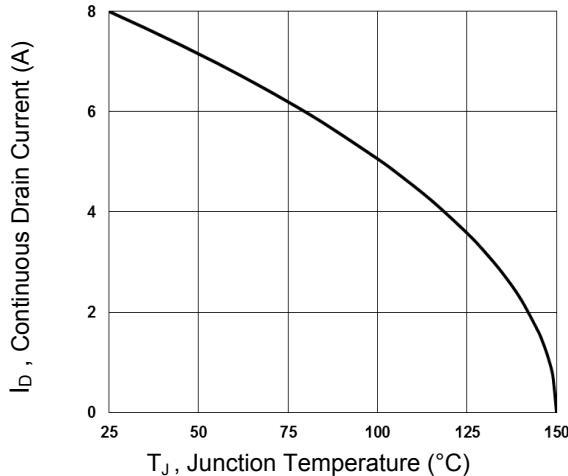


Fig.1 Continuous Drain Current vs. T_c

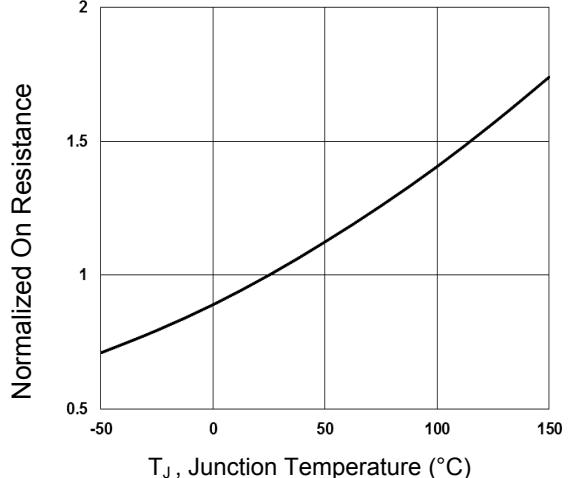


Fig.2 Normalized $R_{DS(ON)}$ vs. T_J

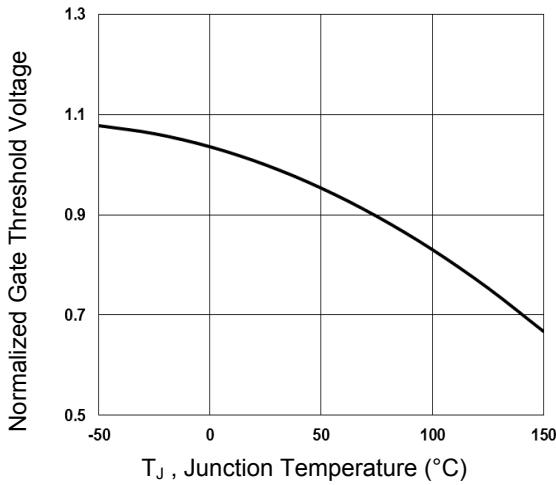


Fig.3 Normalized V_{th} vs. T_J

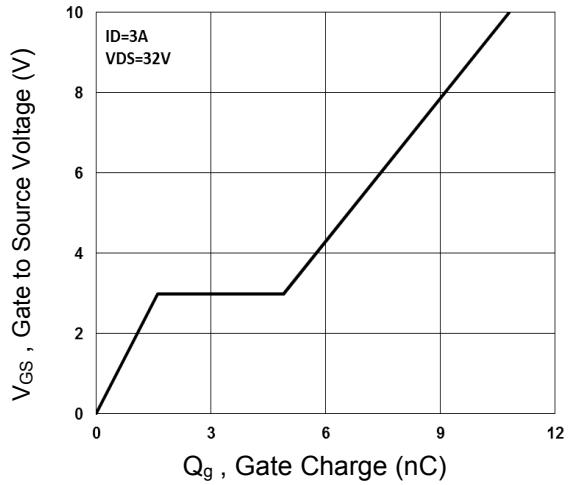


Fig.4 Gate Charge Waveform

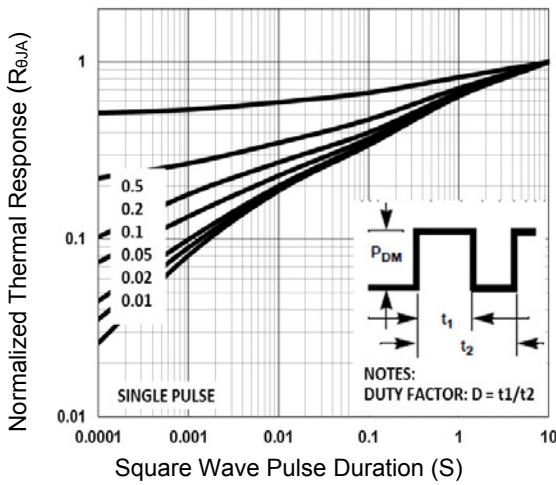


Fig.5 Normalized Transient Impedance

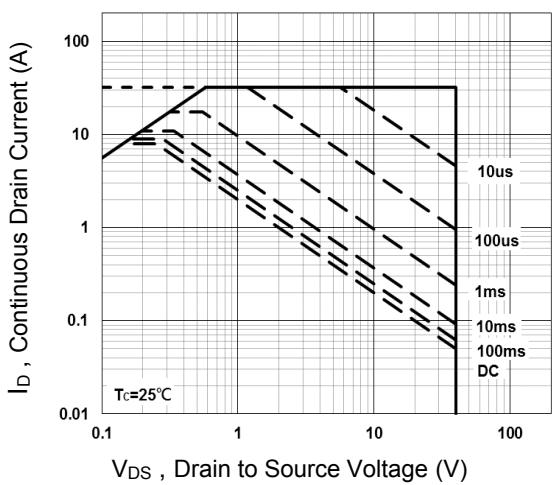


Fig.6 Maximum Safe Operation Area

Typical Electrical and Thermal Characteristic Curves

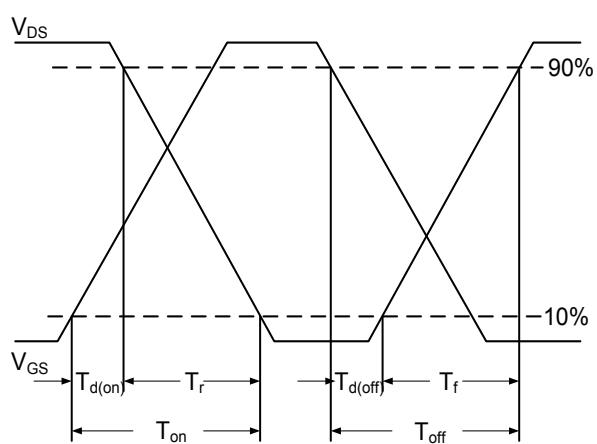


Fig.7 Switching Time Waveform

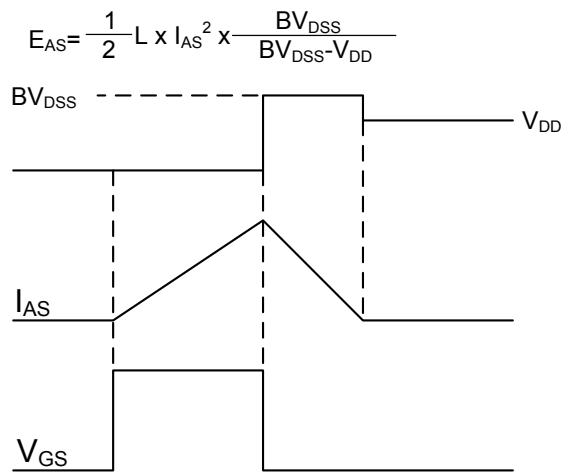
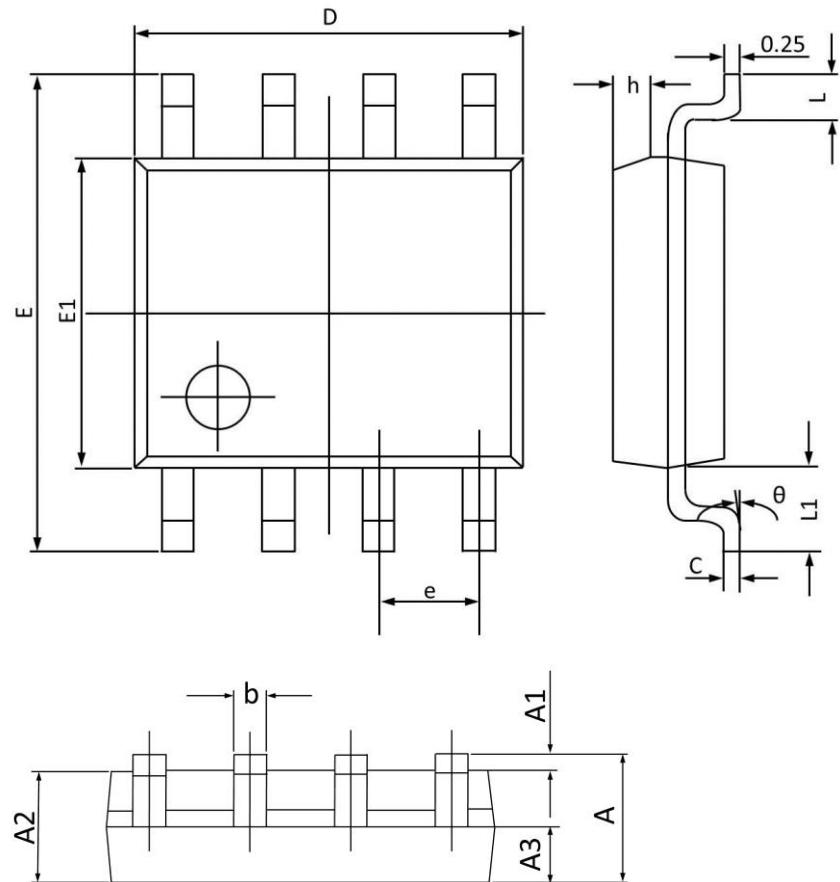


Fig.8 E_{AS} Waveform

Package Outline Dimensions

SOP-8



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.800	0.053	0.069
A1	0.050	0.250	0.002	0.010
A2	1.250	1.650	0.049	0.065
A3	0.500	0.700	0.020	0.028
b	0.300	0.510	0.012	0.020
c	0.150	0.260	0.006	0.010
D	4.700	5.100	0.185	0.201
E	5.800	6.200	0.228	0.244
E1	3.700	4.100	0.146	0.161
e	1.270(BSC)		0.050(BSC)	
h	0.250	0.500	0.010	0.020
L	0.400	1.000	0.016	0.039
L1	1.050(BSC)		0.041(BSC)	
θ	0°	8°	0°	8°